

H7N0405LD, H7N0405LS, H7N0405LM

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1367-0100 Rev.1.00 Sep 25, 2006

Features

- Low on-resistance $R_{DS(on)} = 4.0 \text{ m}\Omega \text{ typ.}$
- Low drive current.
- Capable of 4.5 V gate drive

Outline

RENESAS Package code: PRSS0004AE-A (Package name: LDPAK (L))



H7N0405LD

RENESAS Package code: PRSS0004AE-C (Package name: LDPAK (S)-(2))



H7N0405LM

RENESAS Package code: PRSS0004AE-B (Package name: LDPAK (S)-(1))

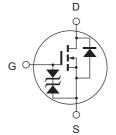


H7N0405LS



1. Gate

- 2. Drain
- 3. Source
- 4. Drain



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Rating	Unit
Drain to source voltage	V _{DSS}	40	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	80	А
Drain peak current	I _D (pulse) ^{Note1}	320	А
Body drain diode reverse drain current	I_{DR}	80	А
Avalanche current	I _{AP} Note3	40	А
Avalanche energy	E _{AR} Note3	213	mJ
Channel dissipation	Pch ^{Note2}	80	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Tc = 25°C

3. Tch = 25°C, Rg \geq 50 Ω

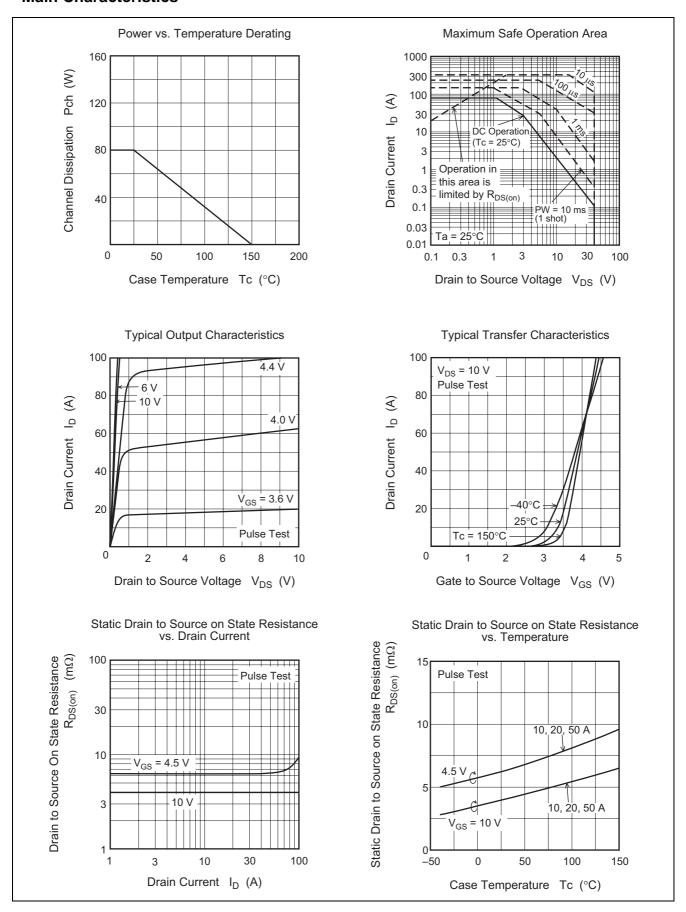
Electrical Characteristics

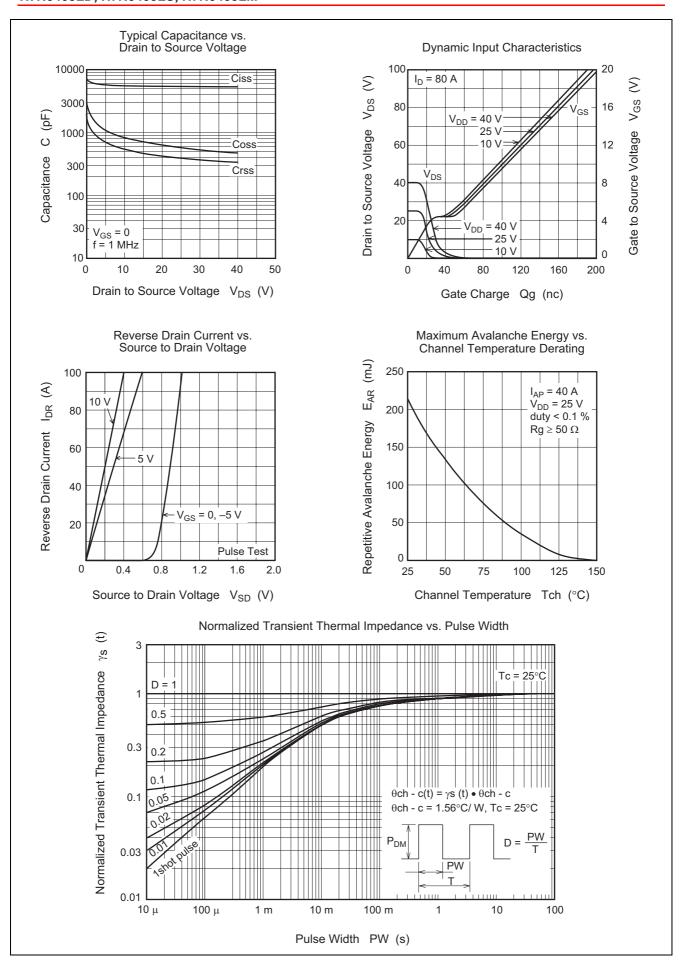
 $(Ta = 25^{\circ}C)$

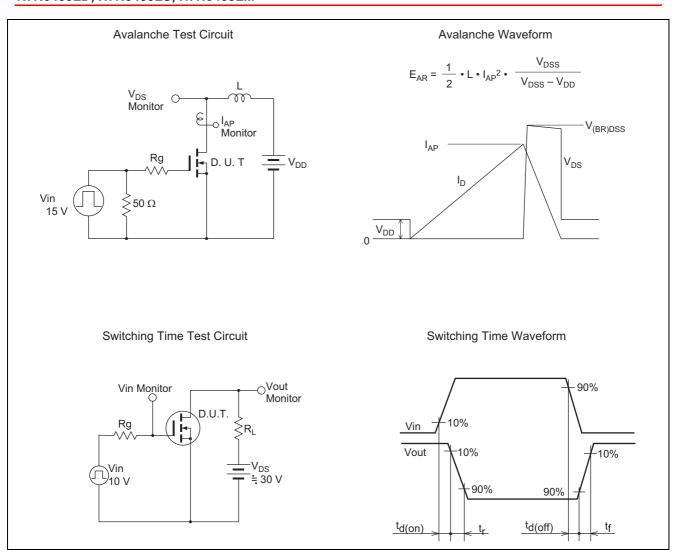
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source break down voltage	$V_{(BR)DSS}$	40	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 40 \text{ V}, V_{GS} = 0$
Gate to source cut off voltage	$V_{GS(off)}$	1.5	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{Note4}$
Static drain to source on state	R _{DS(on)}	_	4.0	5.0	mΩ	$I_D = 40 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
resistance		_	6.2	8.7	mΩ	$I_D = 40 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	54	90	_	S	$I_D = 40 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Input capacitance	Ciss	_	5600	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	825	_	pF	f = 1 MHz
Reverse transfer admittance	Crss	_	550	_	pF	
Total gate charge	Qg	_	100	_	nC	$V_{DD} = 25 \text{ V}, V_{GS} = 10 \text{ V},$
Gate to source charge	Qgs	_	25	_	nC	$I_D = 80 \text{ A}$
Gate to drain charge	Qgd	_	25	_	nC	
Turn-off delay time	t _{d(on)}	_	40	_	ns	$V_{GS} = 10 \text{ V}, I_D = 40 \text{ A},$
Rise time	t _r	_	400	_	ns	$R_L = 0.75 \Omega$, $Rg = 4.7 \Omega$
Body-drain diode forward voltage	t _{d(off)}	_	100	_	ns	
Fall time	t _f	_	26	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.94	_	V	$I_F = 80 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	40	_	ns	$I_F = 80 \text{ A}, V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

Main Characteristics





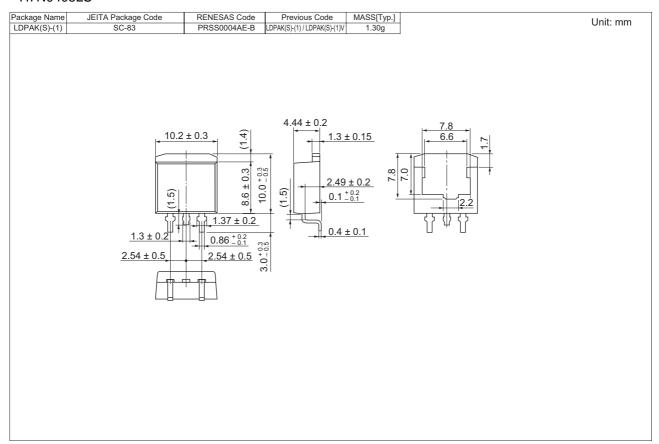


Package Dimensions

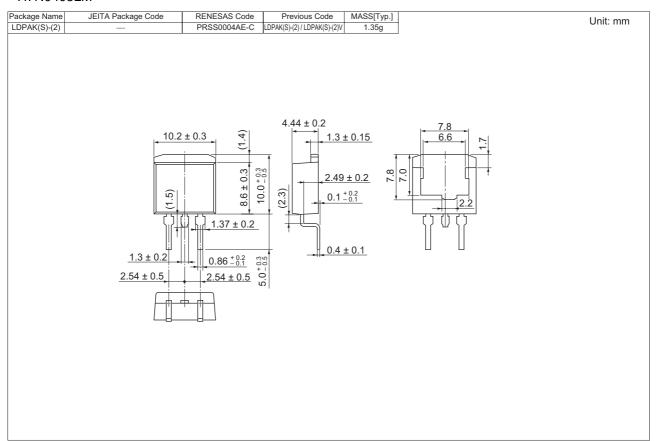
• H7N0405LD

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]	I limite manua
LDPAK(L)	_	PRSS0004AE-A	LDPAK(L) / LDPAK(L)V	1.40g	Unit: mm
		11.3 ± 0.5 10.0 ± 0.3 10.0 ± 0.3 8.6 ± 0.3 2.54 ± 0.5	0.2 ± 0.3 1.3 ± 0.2 1.37 ± 0.2 $0.86^{+0.2}_{-0.1}$ 0.76 ± 0.1 2.54 ± 0.5	11.0 ± 0.5	$ \begin{array}{c} 4.44 \pm 0.2 \\ 1.3 \pm 0.15 \end{array} $ $ 2.49 \pm 0.2 $ $ 0.4 \pm 0.1 $

• H7N0405LS



• H7N0405LM



Ordering Information

Part Name	Quantity	Shipping Container		
H7N0405LD-E	500 pcs	Box (Conductive Sack)		
H7N0405LSTL-E	1000 pcs	Taping		
H7N0405LMTL-E	1000 pcs	Taping		

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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